

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)  
 Contact Info: [ti.com/support](http://ti.com/support)  
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB  
 Created on: 05/16/2022

Details for "SN74BCT374NE4"

**Current Product Information**

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package   Pins	Package body size (mm)	Total device mass (mg)*
SN74BCT374NE4	NIPDAU	Level-NC-NC-NC	TI MALAYSIA A/T	N   20	6.35x24.33x4.57	1679.4

\*Total Device Mass  
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

**Environmental Ratings Information**

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	No	Yes

**Component Information**

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
<b>Bond Wire</b>							
Other Nonferrous Metals and Alloys	Calcium	7440-70-2	0.000001	0.000446	4	0	0
Other Nonferrous Metals and Alloys	Yttrium	7440-65-5	0.000002	0.000893	9	0	0
Precious Metals	Gold	7440-57-5	0.223978	99.997768	999978	0.013337	133
Precious Metals	Silver	7440-22-4	0.000002	0.000893	9	0	0
Sub-Total			0.223983	100	1000000	0.013337	133
<b>Die Attach Adhesive</b>							
Precious Metals	Silver	7440-22-4	0.439055	70.00048	700000	0.026144	261
Thermoplastics	Epoxy	85954-11-6	0.188166	29.99952	300000	0.011204	112
Sub-Total			0.627221	100	1000000	0.037348	373
<b>Lead Frame</b>							
Copper and Its Alloys	Copper	7440-50-8	373.891957	97.701	977010	22.26359	222636
Copper and Its Alloys	Iron	7439-89-6	8.189566	2.14	21400	0.487652	4877
Copper and Its Alloys	Phosphorus	7723-14-0	0.126288	0.033	330	0.00752	75
Zinc and Its Alloys	Zinc	7440-66-6	0.482189	0.126	1260	0.028712	287
Sub-Total			382.69	100	1000000	22.787474	227875
<b>Lead Frame Plating</b>							
Nickel and Its Alloys	Nickel	7440-02-0	29.496712	95.12	951200	1.756397	17564
Precious Metals	Gold	7440-57-5	0.241878	0.78	7800	0.014403	144
Precious Metals	Palladium	7440-05-3	1.27141	4.1	41000	0.075707	757
Sub-Total			31.01	100	1000000	1.846506	18465
<b>Mold Compound</b>							
Other Inorganic Materials	Fused Silica	60676-86-0	899.97645	71.3	713000	53.589563	535896
Other Nonferrous Metals and Alloys	Antimony Trioxide	1309-64-4	5.048956	0.4	4000	0.300643	3006
Other Organic Materials	Brominated Epoxy	40039-93-8	25.244781	2	20000	1.503214	15032
Other Plastics and Rubber	Carbon Black	1333-86-4	3.660493	0.29	2900	0.217966	2180
Thermoplastics	Epoxy	85954-11-6	328.30838	26.01	260100	19.549292	195493
Sub-Total			1262.23906	100	1000000	75.160677	751607
<b>Semiconductor Device</b>							
Ceramics / Glass	Doped Silicon	7440-21-3	2.5973	100	1000000	0.154658	1547
Sub-Total			2.5973	100	1000000	0.154658	1547
<b>Total</b>			1679.387564			100	1000000

**Important Note**

The ppm calculations are at the homogeneous material level and are maximum concentration values. The ppm displayed represents the homogeneous material with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.  
 The ppm calculations are at the component level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the component.  
[See Glossary of Terms for more details.](#)

**Important Part Information**

There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSi or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

**Product Content Methodology**

[For an explanation of the methods used to determine material weights, See Product Content Methodology](#)

**Material Declaration Certificate for Semiconductor IC Packaged Products**

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

**Important Information/Disclaimer**

TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."

[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

Name/Title: Hubie Payne, Vice President, Worldwide SC Quality  
 For further environmental statements, please go to [www.ti.com/ecoinfo](http://www.ti.com/ecoinfo)  
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**RoHS:** Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1 % by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

**RoHS Exempt:** Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

**Green:** Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet JS709B low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.